

said substrate, characterized in that said heat conductive resin layer contains a binder resin, and a heat conductive filler dispersed in said binder resin.

5. (First Amendment) A heat conductive sheet according to claim 1, wherein said binder resin comprises at least one resin selected from a silicone gel resin, a urethane resin, a synthetic rubber resin, and an acrylic thermoplastic resin.

10. (First Amendment) A method of producing a heat conductive sheet including a substrate and a heat conductive resin layer applied to at least one surface of said substrate, comprising the steps of supporting said substrate by a support; applying a film-forming resin composition containing a binder resin and a heat conductive filler to a non-supporting surface of said substrate to form a heat conductive resin layer; and separating the resulting heat conductive sheet from said support; wherein said substrate has a thickness from 1 to 12 μm .

Please add new claims 11-17:

11. (New) A heat conductive sheet according to claim 1, wherein said heat conductive resin layer is applied to only one surface of said substrate.

12. (New) The method of claim 10 wherein the heat conductive resin layer is applied to only one surface of said substrate.

13. (New) The method of claim 10 further comprising applying a release liner to the film-forming resin composition to form a laminate.

14. (New) The method of claim 13 further comprising applying heat and pressure to the laminate before the step of separating the support.

15. (New) The method of claim 10 wherein the heat conductive resin layer is cured.

16. (New) The method of claim 10 further comprising providing an adhesive film on the support beneath the substrate.

17. (New) The method of claim 13 further comprising providing an adhesive film on the support beneath the substrate.

A version marked up to show changes made to the claims relative to the previous version of the claims is attached.